



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006				
CUSTOMER:			DIE SIZE:					
WIRE TYPE/ SIZE:			NO. OF WIRES:					
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES DO NOT SCALE DRAWING	REVISIONS					24 Lead 300 mils SOIC Open-Pak Bonding Diagram		
	ECN NO.	DATE	DESCRIPTION	APPROVED				
	10516	11/2/05	PRODUCTION RELEASE	D.BENANDO		SIZE	PART NO.	REV
DRAWN BY	W. GRIFFITTS	DATE	11/1/05	PACKAGE SIZE:	0.610" x 0.295"	A	SOIC300-24-OP-01	2
APP BY	P. FLASKERUD	DATE	11/1/05	DIE PAD SIZE:	0.220" x 0.150"	SCALE	CAD FILE	SHEET
						24X	SOIC300-24-OP-01-B-R2.DWG	1 OF 1